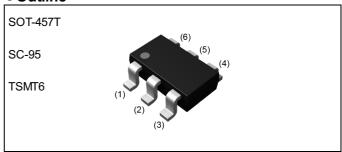
Pch -30V -3.0A Middle Power MOSFET

V _{DSS}	-30V
R _{DS(on)} (Max.)	91mΩ
I _D	±3.0A
P _D	1.25W

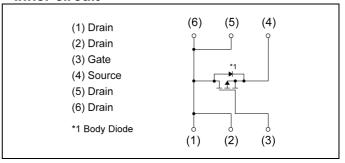
● Features

- 1) Low on resistance.
- 2) Small Surface Mount Package (TSMT6).
- 3) Pb-free lead plating; RoHS compliant

Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TR
	Marking	JS

Application

Switching

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-30	V
Continuous drain current	I _D *1	±3.0	А
Pulsed drain current	I _{DP} *2	±12	Α
Gate - Source voltage	V _{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *3	-3.0	А
Avalanche energy, single pulse	E _{AS} *3	3.3	mJ
Power dissipation	P _D *4	1.25	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			l limit
Parameter		Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJA} *4	-	100	•	°C/W

● Electrical characteristics (T_a = 25°C)

Darameter	Sumb of	Conditions	Values			Linit	
Parameter Symbol		Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}}$	I _D = 1mA referenced to 25°C	-	-22	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA	
Gate - Source leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -1$ mA	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	2.9	-	mV/°C	
Static drain - source	D *5	$V_{GS} = -10V, I_D = -3.0A$	-	70	91	m0	
on - state resistance	R _{DS(on)} *5	$V_{GS} = -4.5V, I_D = -3.0A$	-	104	135	mΩ	
Forward Transfer Admittance	Y _{fs} *5	$V_{DS} = -5V, I_{D} = -3.0A$	2.4	-	-	S	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10µs, Duty cycle \leq 1%

^{*3} L \simeq 0.5mH, V_{DD} = -15V, R_G = 25 Ω , STARTING T_{ch} = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Mounted on a ceramic boad (30×30×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Doromotor	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	1	240	1	
Output capacitance	C _{oss}	V _{DS} = -15V	-	45	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	35	-	
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ -15V,V _{GS} = -10V	-	6.5	-	
Rise time	t _r *5	I _D = -1.5A	-	8.5	-	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 10\Omega$	-	22	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	5.5	-	

● Gate charge characteristics (T_a = 25°C)

	· u						
Parameter	Symbol	Conditi	Conditions		Values		
Parameter	Symbol	ol Conditions		Min.	Тур.	Max.	Unit
Total gate charge	O *5		V _{GS} = -10V	-	5.4	-	
Total gate charge	Q_g^{*5}	$V_{DD} \simeq -15V$ $I_{D} = -3.0A$		-	2.7	-	" C
Gate - Source charge	Q _{gs} *5		V _{GS} = -4.5V	-	0.8	-	nC
Gate - Drain charge	Q _{gd} *5			-	1.0	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol Conditions		Values			Unit	
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offit	
Continuous forward current	I _S *1	T = 25°C	-	-	-1.0	Α	
Pulse forward current	I _{SP} *2	⁻ T _a = 25°C	-	-	-12	Α	
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = -1.0A	-	-	-1.2	V	

Fig.1 Power Dissipation Derating Curve

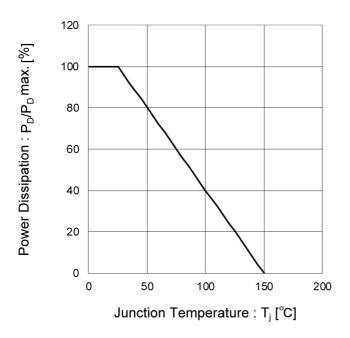
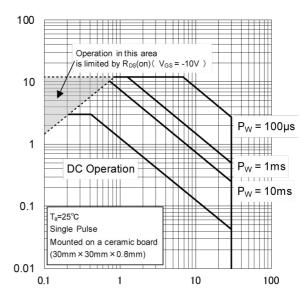


Fig.2 Maximum Safe Operating Area



Drain Current: -l_D [A]

Drain - Source Voltage: -VDS [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

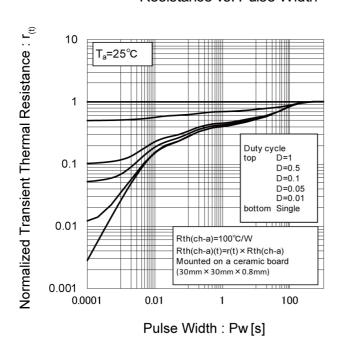
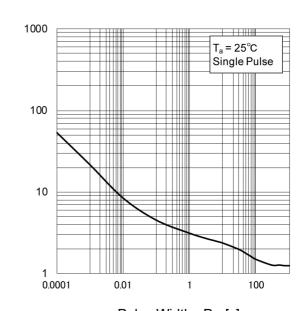


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width : Pw [s]

Peak Transient Power: P(W)

Fig.5 Typical Output Characteristics(I)

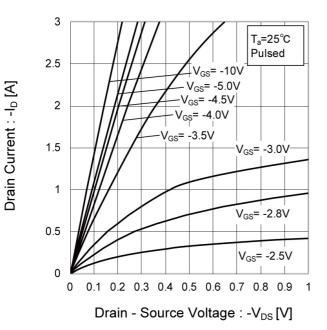
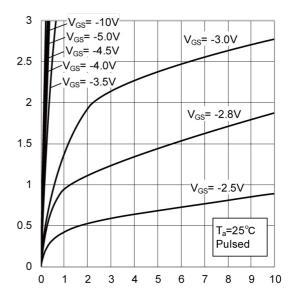


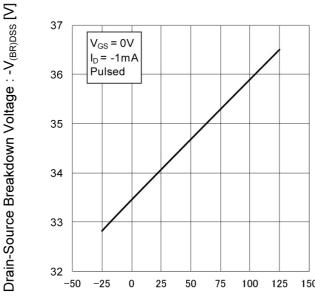
Fig.6 Typical Output Characteristics(II)



Drain Current : -I_D [A]

Drain - Source Voltage : -V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



150

Junction Temperature : T_i [°C]

Fig.8 Typical Transfer Characteristics

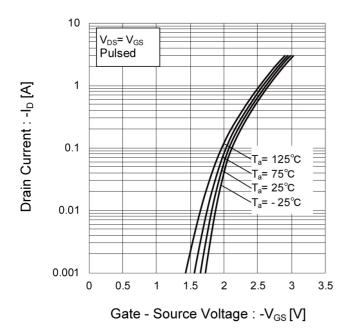


Fig.9 Gate Threshold Voltage vs. Junction Temperature

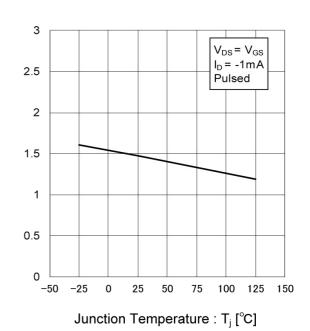
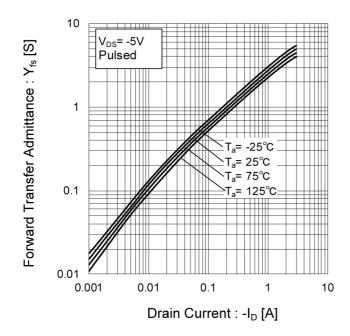


Fig.10 Transconductance vs. Drain Current



Gate Threshold Voltage : - $V_{GS(th)}$ [V]

Fig.11 Drain Current Derating Curve

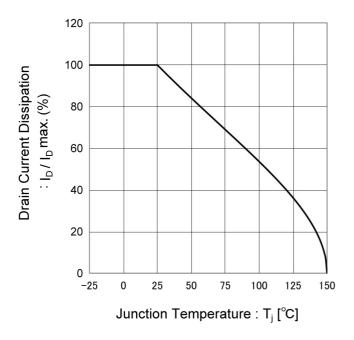


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

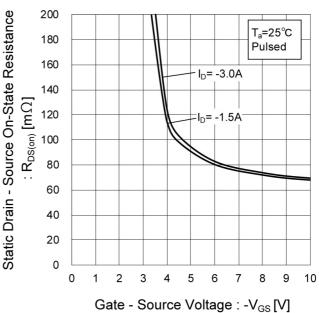


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

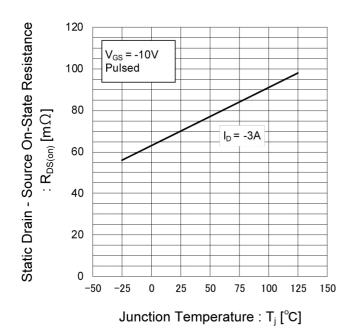


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

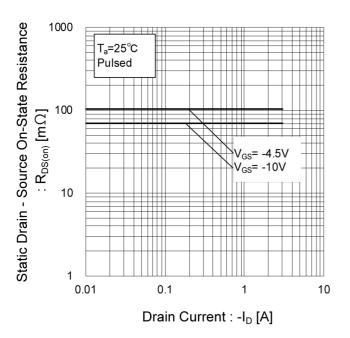


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

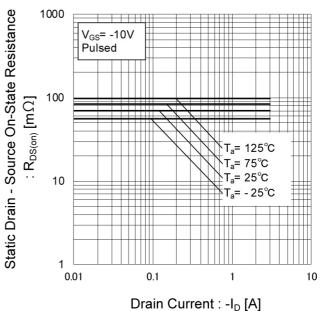


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

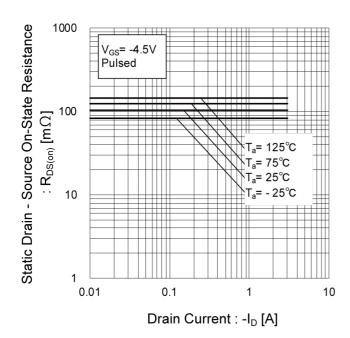


Fig.17 Typical Capacitance vs. Drain - Source Voltage

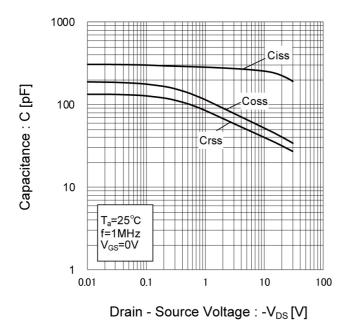


Fig.18 Switching Characteristics

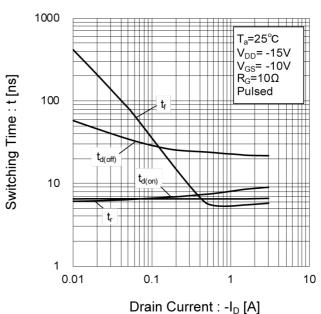


Fig.19 Dynamic Input Characteristics

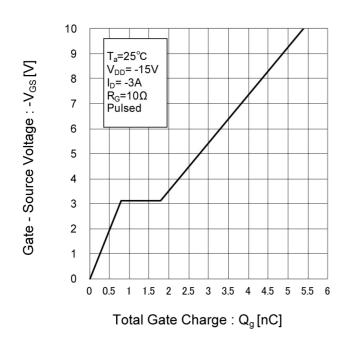
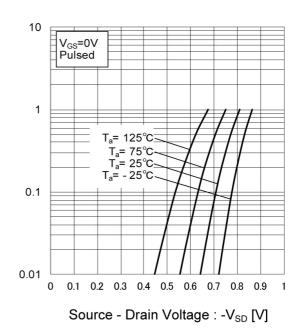


Fig.20 Source Current vs. Source Drain Voltage



9/11

Source Current : -I_s [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

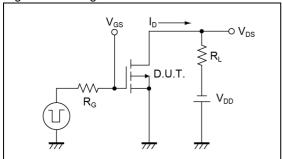


Fig.2-1 Gate Charge Measurement Circuit

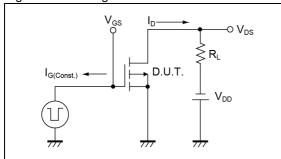


Fig.3-1 Avalanche Measurement Circuit

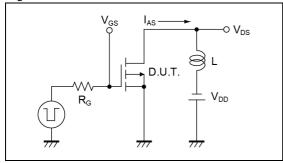


Fig.1-2 Switching Waveforms

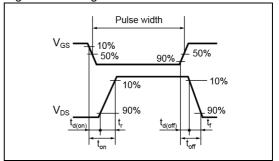


Fig.2-2 Gate Charge Waveform

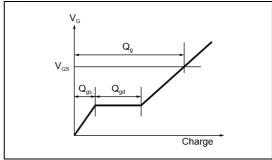
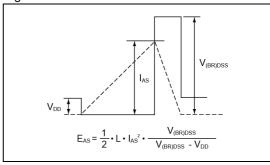
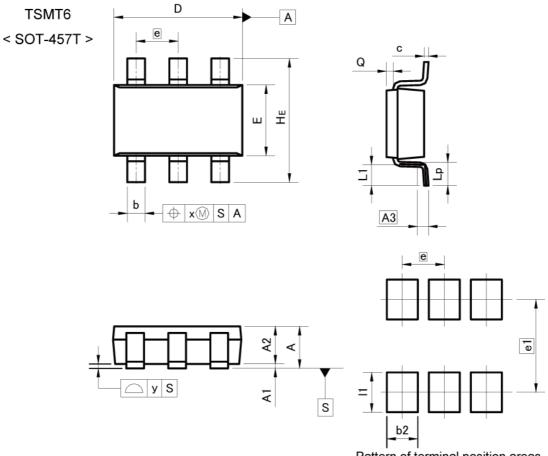


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1-	1.00	ı	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.:	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.0	37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
х	_	0.20	-	0.008
У	-	0.10	_	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2		0.70	_	0.028
e1	2.10		0.0	83
11	0 	0.90	-	0.035

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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RQ6E030AT - Web Page

Distribution Inventory

Part Number	RQ6E030AT
Package	TSMT6
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes